



SOT1260-1

plastic, thermal enhanced super thin small outline package;
no leads; 8 terminals; body 1.5 mm x 1.5 mm x 0.3 mm

13 December 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HX2SON
Package type industry code	HX2SON8
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	11-6-2014
Manufacturer package code	SOT1260

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.45	-	1.5	1.55	mm
E	package width	1.45	-	1.5	1.55	mm
A	seated height	0.28	-	0.3	0.33	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	8	-	

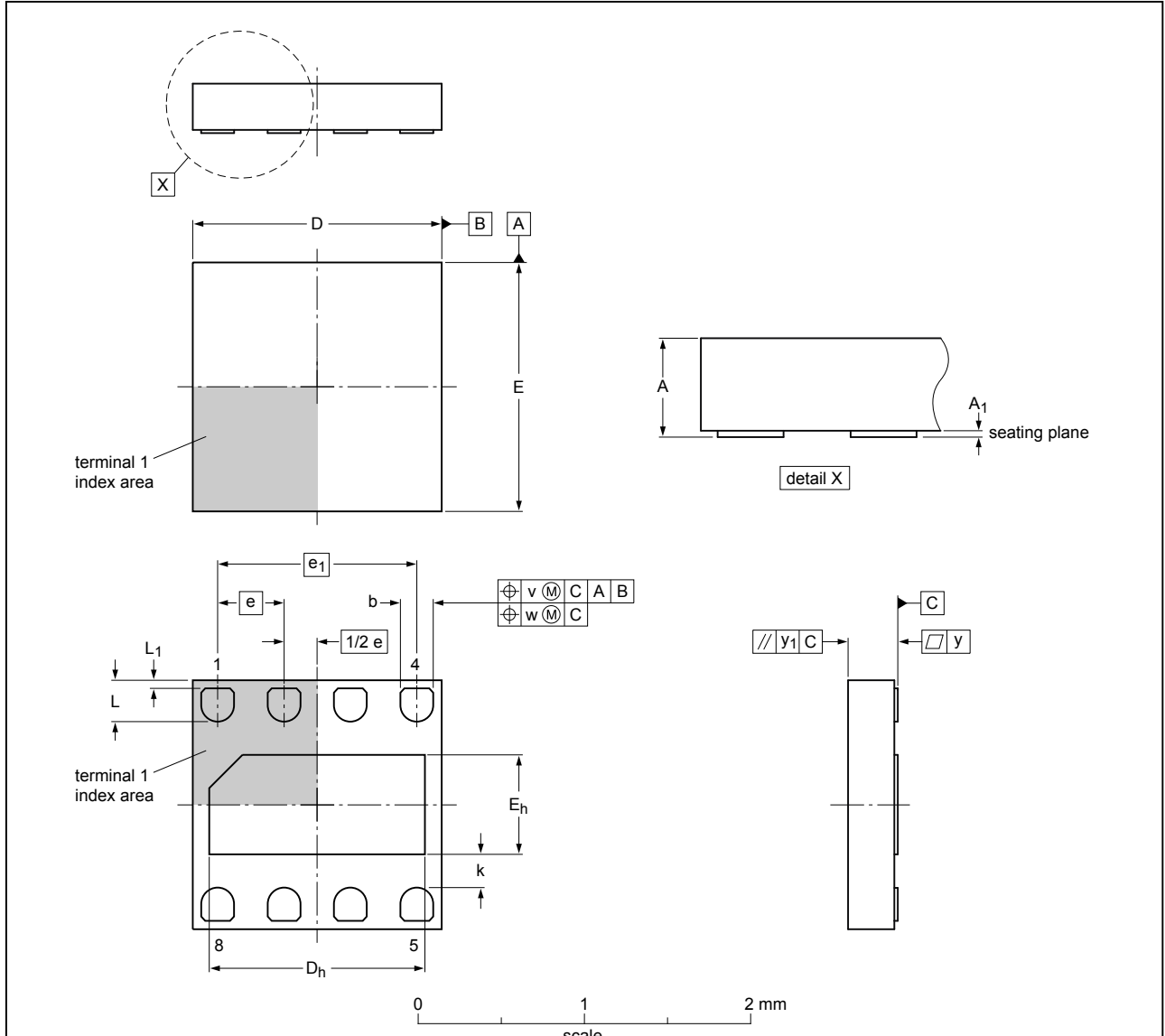


plastic, thermal enhanced super thin small outline package; no leads; 8 terminals; body 1.5 mm x 1.5 mm x 0.3 mm

2. Package outline

HX2SON8: plastic, thermal enhanced super thin small outline package; no leads; 8 terminals; body 1.5 x 1.5 x 0.3 mm

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Dimensions: (mm are the original dimensions)

Unit	A	A ₁	b	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	k	L	L ₁	v	w	y	y ₁
max	0.33	0.05	0.25	1.55	1.40	1.55	0.70				0.35	0.10				
nom	0.30	0.02	0.20	1.50	1.30	1.50	0.60	0.4	1.2	0.20	0.25	0.05	0.07	0.05	0.05	0.05
min	0.28	0.00	0.15	1.45	1.15	1.45	0.45			0.15	0.15	0.00				

Note
1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot1260-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1260-1		MO-255			-14-06-11- 16-01-13

Fig. 1. Package outline HX2SON8 (SOT1260-1)

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3. Soldering

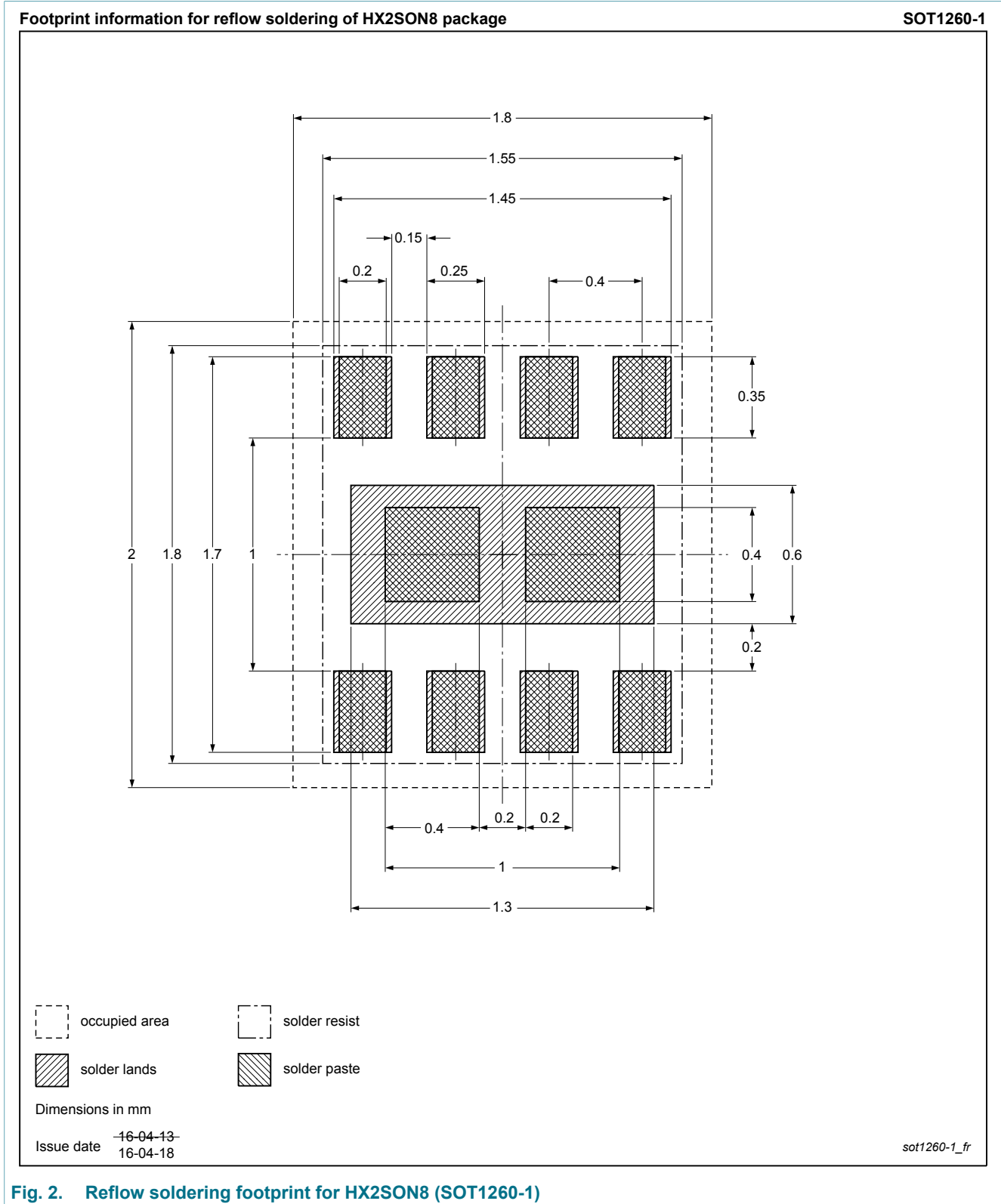


Fig. 2. Reflow soldering footprint for HX2SON8 (SOT1260-1)

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4. Legal information

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